SCAS213A - MAY 1987 - REVISED APRIL 1996

- Eight Latches in a Single Package
- 3-State Bus-Driving True Outputs
- Full Parallel Access for Loading
- Buffered Control Inputs
- Flow-Through Architecture Optimizes
 PCB Layout
- Center-Pin V_{CC} and GND Configurations Minimize High-Speed Switching Noise
- EPIC™ (Enhanced-Performance Implanted CMOS) 1-μm Process
- 500-mA Typical Latch-Up Immunity at 125°C
- Package Options Include Plastic Small-Outline (DW) and Shrink Small-Outline (DB) Packages, and Standard Plastic 300-mil DIPs (NT)

24 1 OE 2Q**∏** 23∏1D 3Q∏ 3 22 1 2D 4Q**∏** 4 21 3D GND∏ 5 20 T 4D 19 V_{CC} GND∏ 6 18 V_{CC} GND 7 GND 1 8 17 5D 5Q∏ 9 16 ¶ 6D 6Q 10 15**∏** 7D 7Q**∏** 11 14 \ 8D 12 13 ∏ LE 8Q∏

DB, DW, OR NT PACKAGE (TOP VIEW)

description

This 8-bit latch features 3-state outputs designed specifically for driving highly-capacitive or relatively low-impedance loads. It is particularly suitable for implementing buffer registers, I/O ports, bidirectional bus drivers, and working registers.

The eight latches of the 74AC11373 are transparent D-type latches. While the latch-enable (LE) input is high, the Q outputs follow the data (D) inputs. When LE is taken low, the Q outputs are latched at the levels set up at the D inputs.

OE can be used to place the eight outputs in either a normal logic state (high or low logic levels) or a high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. The high-impedance third state and increased drive provide the capability to drive bus lines in a bus-organized system without need for interface or pullup components.

OE does not affect the internal operations of the latches. Old data can be retained or new data can be entered while the outputs are off.

The 74AC11373 is characterized for operation from -40°C to 85°C.

FUNCTION TABLE (each latch)

	INPUTS		OUTPUT
ŌĒ	LE	D	Q
L	Н	Н	Н
L	Н	L	L
L	L	Χ	Q ₀
Н	Χ	Χ	Z

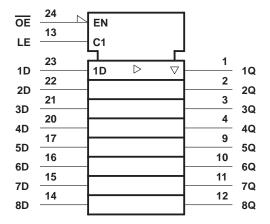


Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

EPIC is a trademark of Texas Instruments Incorporated

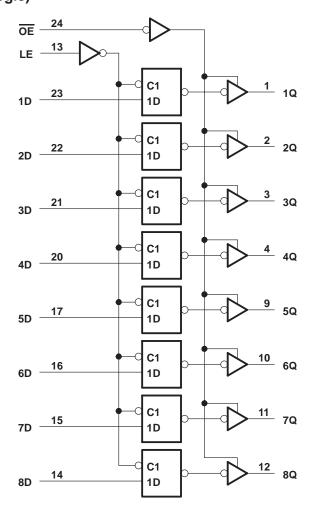


logic symbol†



[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)





SCAS213A - MAY 1987 - REVISED APRIL 1996

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}		0.5 V to 6 V
Input voltage range, V _I (see Note 1)		$-0.5 \text{ V to V}_{CC} + 0.5 \text{ V}$
Output voltage range, VO (see Note 1)		. $-0.5 \text{ V to V}_{CC} + 0.5 \text{ V}$
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$)		±20 mA
Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{CC}$)		±50 mA
Continuous output current, I_O ($V_O = 0$ to V_{CC})		±50 mA
Continuous current through V _{CC} or GND		±200 mA
Maximum power dissipation at $T_A = 55^{\circ}C$ (in still air) (see Note 2): I	DB package	0.65 W
	DW package	1.7 W
1	NT package	1.3 W
Storage temperature range, T _{stq}		65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

2. The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils, except for the NT package, which has a trace length of zero.

recommended operating conditions

			MIN	NOM	MAX	UNIT	
VCC	Supply voltage		3	5	5.5	V	
	High-level input voltage	V _{CC} = 3 V	2.1				
ViH		V _{CC} = 4.5 V	3.15			V	
		V _{CC} = 5.5 V	3.85				
		V _{CC} = 3 V			0.9		
VIL	V _{CC} = 5.5 \	V _{CC} = 4.5 V			1.35	V	
		V _{CC} = 5.5 V			1.65	<u> </u>	
VI	Input voltage		0		VCC	V	
Vo	Output voltage		0		VCC	V	
		V _{CC} = 3 V			-4		
IOH	High-level output current	V _{CC} = 4.5 V			-24	mA	
		V _{CC} = 5.5 V			-24		
		V _{CC} = 3 V			12		
lOL	Low-level output current	V _{CC} = 4.5 V			24	mA	
		V _{CC} = 5.5 V			24		
A 4 / A	land the solition with a suffill units	ŌĒ	0		5	0/	
Δt/Δv	Input transition rise or fall rate Data, I		0		10	ns/V	
TA	Operating free-air temperature		-40		85	°C	

74AC11373 OCTAL TRANSPARENT D-TYPE LATCH WITH 3-STATE OUTPUTS

SCAS213A - MAY 1987 - REVISED APRIL 1996

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

24244555	TEGT CONDITIONS	1,,	T,	Δ = 25°C	;	BAIN		
PARAMETER	TEST CONDITIONS	VCC	MIN	TYP	MAX	MIN	MAX	UNIT
		3 V	2.9			2.9		
	$I_{OH} = -50 \mu\text{A}$	4.5 V	4.4			4.4		
		5.5 V	5.4			5.4		
Voн	$I_{OH} = -4 \text{ mA}$	3 V	2.58			2.48		V
	Jan. 24 mA	4.5 V	3.94			3.8		
	$I_{OH} = -24 \text{ mA}$		4.94			4.8		
	$I_{OH} = -75 \text{ mA}^{\dagger}$	5.5 V				3.85		
	I _{OL} = 50 μA				0.1		0.1	
					0.1		0.1	
					0.1		0.1	
VOL	I _{OL} = 12 mA	3 V			0.36		0.44	V
	I _{OL} = 24 mA				0.36		0.44	
					0.36		0.44	
	$I_{OL} = 75 \text{ mA}^{\dagger}$	5.5 V					1.65	
loz	$V_O = V_{CC}$ or GND	5.5 V			±0.5		±5	μΑ
lį	V _I = V _{CC} or GND	5.5 V			±0.1		±1	μΑ
Icc	$V_I = V_{CC}$ or GND, $I_O = 0$	5.5 V			8		80	μΑ
Ci	$V_I = V_{CC}$ or GND	5 V		4				pF
Co	$V_O = V_{CC}$ or GND	5 V		10				pF

The Not more than one output should be tested at a time, and the duration of the test should not exceed 10 ms.

timing requirements over recommended operating free-air temperature range, V_{CC} = 3.3 V \pm 0.3 V (unless otherwise noted) (see Figure 1)

		T _A = 25°C		,C		
		MIN	MAX	MIN	MAX	UNIT
t _W	Pulse duration, LE high	5.5		5.5		ns
t _{su}	Setup time, data before LE↓	4		4		ns
th	Hold time, data after LE↓	2		2		ns

timing requirements over recommended operating free-air temperature range, V_{CC} = 5 V \pm 0.5 V (unless otherwise noted) (see Figure 1)

		T _A = 25°C		T _A = 25°C		MAIN	MAY	LINUT
		MIN	MAX	MIN	MAX	UNIT		
t _W	Pulse duration, LE high	4		4		ns		
t _{su}	Setup time, data before LE↓	3.5		3.5		ns		
th	Hold time, data after LE↓	2		2		ns		

SCAS213A - MAY 1987 - REVISED APRIL 1996

switching characteristics over recommended operating free-air temperature range, V_{CC} = 3.3 V \pm 0.3 V (unless otherwise noted) (see Figure 1)

DADAMETED	FROM	то	T,	4 = 25°C	;	MAINI	MAY	LINUT
PARAMETER	(INPUT)	(OUTPUT)	MIN	TYP	MAX	MIN	MAX	UNIT
t _{PLH}	D	0	1.5	9	13.1	1.5	14.8	20
^t PHL	D	Q	1.5	8	10.6	1.5	11.7	ns
^t PLH	LE	An., O	1.5	10	14.5	1.5	16.3	
t _{PHL}		Any Q	1.5	9.5	12.8	1.5	14.2	ns
^t PZH	ŌĒ		1.5	9	13.1	1.5	14.7	
^t PZL	OE	Any Q	1.5	8.5	11.6	1.5	13.1	ns
^t PHZ	ŌĒ	Any O	1.5	9.5	12	1.5	12.7	20
t _{PLZ}	OE .	Any Q	1.5	7.5	10.2	1.5	10.8	ns

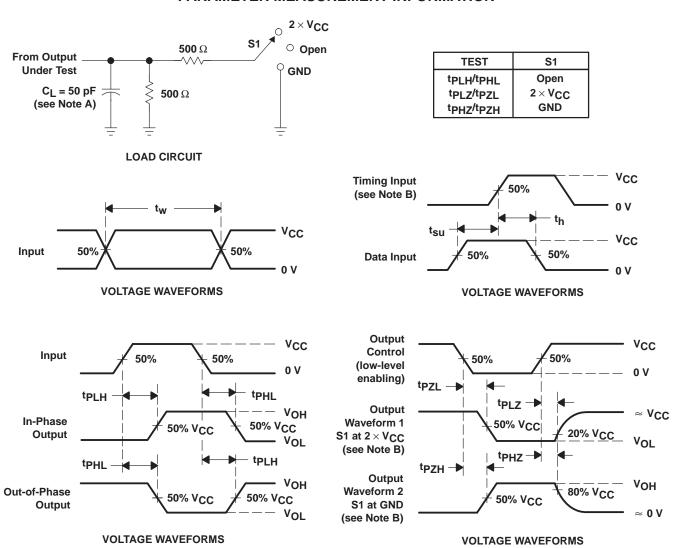
switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V \pm 0.5 V (unless otherwise noted) (see Figure 1)

•		, ,						
DADAMETED	FROM	то	T _A = 25°C				LINUT	
PARAMETER	(INPUT)	(OUTPUT)	MIN	TYP	MAX	MIN	MAX	UNIT
^t PLH		_	1.5	6	8.9	1.5	10.3	
^t PHL	D	Q	1.5	5.5	7.6	1.5	8.4	ns
^t PLH	- LE	Any 0	1.5	6.5	10	1.5	11.3	20
t _{PHL}		Any Q	1.5	6.5	9.1	1.5	10.2	ns
^t PZH	ŌĒ	A O	1.5	6.5	9.5	1.5	10.8	
^t PZL	OE	Any Q	1.5	6	8.6	1.5	9.7	ns
^t PHZ	ŌĒ	A O	1.5	8.5	10.6	1.5	11.1	
t _{PLZ}	OE .	Any Q	1.5	6	8.2	1.5	8.7	ns

operating characteristics, $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$

PARAMETER			TEST CO	TYP	UNIT	
O Bourse discinction compating a model of		Outputs enabled	0 50 5	(4 MIL-	47	
Cpd	Power dissipation capacitance per latch	Outputs disabled	$C_L = 50 \text{ pF},$	f = 1 MHz	36	pF

PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, $Z_O = 50 \ \Omega$, $t_f = 3 \ ns$, $t_f = 3 \ ns$.
- D. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms







i.com 30-Mar-2005

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
74AC11373DBLE	OBSOLETE	SSOP	DB	24	TBD	Call TI	Call TI
74AC11373DBR	OBSOLETE	SSOP	DB	24	TBD	Call TI	Call TI
74AC11373DW	OBSOLETE	SOIC	DW	24	TBD	Call TI	Call TI
74AC11373DWR	OBSOLETE	SOIC	DW	24	TBD	Call TI	Call TI
74AC11373NT	OBSOLETE	PDIP	NT	24	TBD	Call TI	Call TI

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS) or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

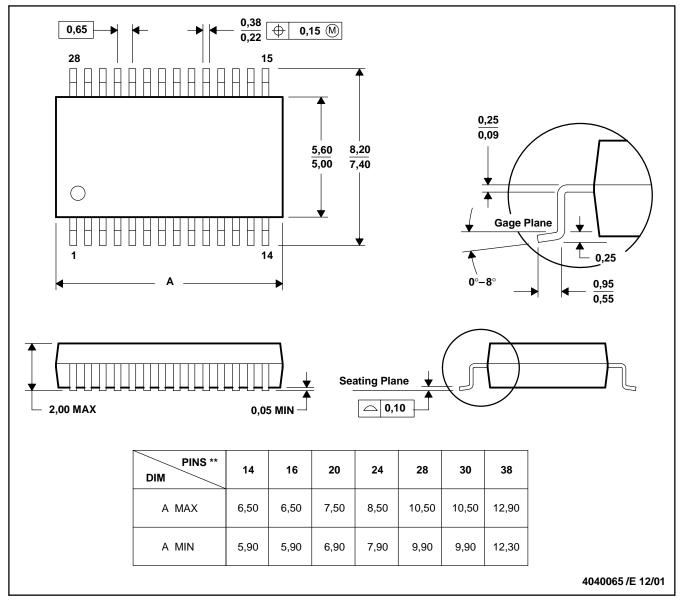
Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

DB (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

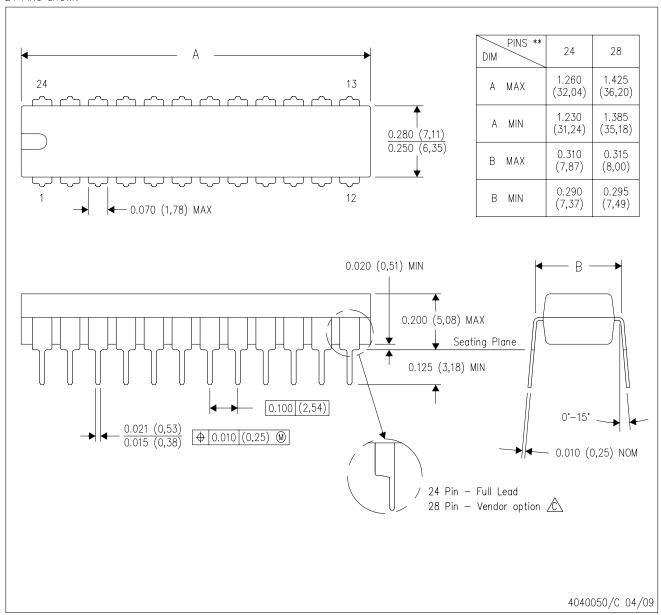
C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-150

NT (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

24 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.

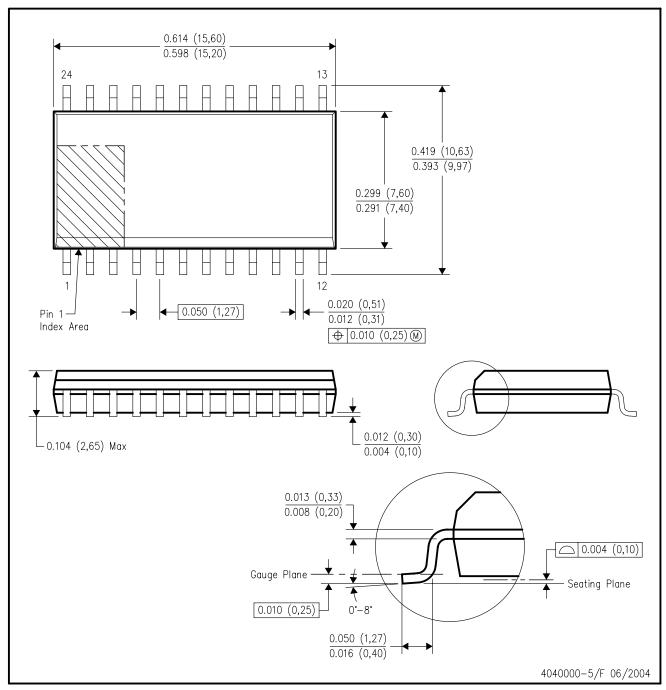
B. This drawing is subject to change without notice.

The 28 pin end lead shoulder width is a vendor option, either half or full width.



DW (R-PDSO-G24)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-013 variation AD.



IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, modifications, enhancements, improvements, and other changes to its products and services at any time and to discontinue any product or service without notice. Customers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All products are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its hardware products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by government requirements, testing of all parameters of each product is not necessarily performed.

TI assumes no liability for applications assistance or customer product design. Customers are responsible for their products and applications using TI components. To minimize the risks associated with customer products and applications, customers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any TI patent right, copyright, mask work right, or other TI intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information published by TI regarding third-party products or services does not constitute a license from TI to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. Reproduction of this information with alteration is an unfair and deceptive business practice. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions

Resale of TI products or services with statements different from or beyond the parameters stated by TI for that product or service voids all express and any implied warranties for the associated TI product or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

TI products are not authorized for use in safety-critical applications (such as life support) where a failure of the TI product would reasonably be expected to cause severe personal injury or death, unless officers of the parties have executed an agreement specifically governing such use. Buyers represent that they have all necessary expertise in the safety and regulatory ramifications of their applications, and acknowledge and agree that they are solely responsible for all legal, regulatory and safety-related requirements concerning their products and any use of TI products in such safety-critical applications, notwithstanding any applications-related information or support that may be provided by TI. Further, Buyers must fully indemnify TI and its representatives against any damages arising out of the use of TI products in such safety-critical applications.

TI products are neither designed nor intended for use in military/aerospace applications or environments unless the TI products are specifically designated by TI as military-grade or "enhanced plastic." Only products designated by TI as military-grade meet military specifications. Buyers acknowledge and agree that any such use of TI products which TI has not designated as military-grade is solely at the Buyer's risk, and that they are solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI products are neither designed nor intended for use in automotive applications or environments unless the specific TI products are designated by TI as compliant with ISO/TS 16949 requirements. Buyers acknowledge and agree that, if they use any non-designated products in automotive applications, TI will not be responsible for any failure to meet such requirements.

Following are URLs where you can obtain information on other Texas Instruments products and application solutions:

Applications Products Amplifiers amplifier.ti.com Audio www.ti.com/audio Data Converters Automotive www.ti.com/automotive dataconverter.ti.com DLP® Products Broadband www.dlp.com www.ti.com/broadband DSP Digital Control dsp.ti.com www.ti.com/digitalcontrol Clocks and Timers www.ti.com/clocks Medical www.ti.com/medical Military Interface www.ti.com/military interface.ti.com Optical Networking Logic logic.ti.com www.ti.com/opticalnetwork Power Mgmt power.ti.com Security www.ti.com/security Telephony Microcontrollers microcontroller.ti.com www.ti.com/telephony Video & Imaging www.ti-rfid.com www.ti.com/video RF/IF and ZigBee® Solutions www.ti.com/lprf Wireless www.ti.com/wireless

> Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265 Copyright © 2009, Texas Instruments Incorporated